



SCWL252012 Series

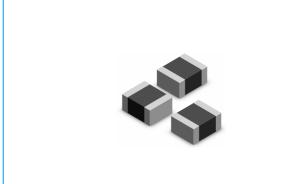
Features

- High saturation current realized by material properties and structure design
- Low DC resistance to achieve high conversion efficiency and low temperature rising
- u Low profile: 2.5mm×2.0mm×1.2mm
- Magnetically shielded structure to accomplish high resolution in EMC protection
- u Halogen free, Lead free, RoHS compliance



SCWL series is generic applied in portable DC to DC converter line.

- u Smart Phone, PAD
- u DC/DC converter
- u Thin-type power supply module



General Technical Data

Operating Temperature Range		-40 ~ +125°C	
Storage Temperature Range		-50 ~ +125°C	
	Storage Temperature	5 ~ 40°C	
Taping package Storage condition	Relative Humidity	< 65%	
	Storage Time	12 Months max	

Part Numbering

SCWL	2520	12	R47	M	T	F
		_		_		_
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- 1 Series Name, wire-wound type power inductor
- 2 Size Code: the first two digitals : length(mm), the last two digitals : width(mm)
- 3 Thickness (mm)
- 4 Inductance (μ H), eg. 2R2=2.2 μ H; R47=0.47 μ H
- 5 Inductance tolerance, M: ±20%
- 6 Packaging: T Embossed plastic tape, 7" reel.
- 7 Soldering: Green Parts, F Lead-Free for whole chip

1/5





SCWL252012 Series

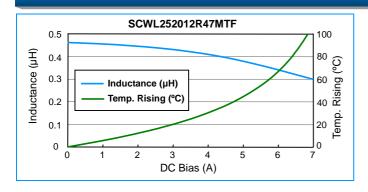
Electrical Characteristics

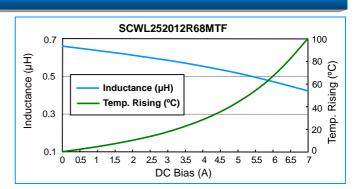
Part Number	Initial Inductance	DC Resistance R_{DC} (m Ω)		Saturation Current Isat (A)		Heat Rating Current Irms (A)	
	Li (µH) @1mA	Typical	Maximum	Typical	Maximum	Typical	Maximum
SCWL252012R47MTF	0.47	22	28	6	5.5	4.5	4.0
SCWL252012R68MTF	0.68	30	38	5.5	5	4.3	3.9
SCWL2520121R0MTF	1.0	44	54	4.5	4	3.1	2.7
SCWL2520122R2MTF	2.2	85	102	3	2.7	2.3	2.0

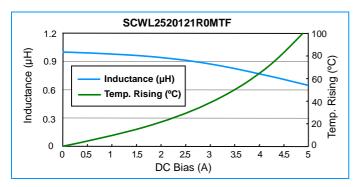
Note:

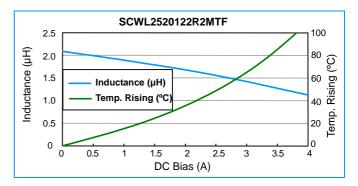
- 1. All test data is referenced to 26 °C ambient.
- 2. Inductance is measured by LCR meter, Test frequency at 1MHz
- 3. Inductance Tolerance: ±20%.
- 4. DC resistance is measured by micro-ohm meter.
- 5. Isat means that DC current will cause a 30% inductance reduction form initial value.
- 6. Irms means that DC current will cause coil temperature rising to 40 °C whichever is smaller.

Current Characteristics







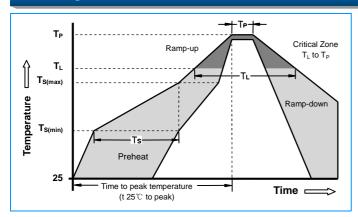






SCWL252012 Series

Soldering Parameters



Precaution for Soldering

Note that this product will be easily damaged by rapid heating, rapid cooling or local heating.

Do not give heat shock over 100°C in the process of soldering. We recommend to take preheating and gradual cooling

Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

1) The tip temperature must be less than 280 for the period.

- 1) The tip temperature must be less than 280 for the period within 3 seconds by using soldering gun under 30W
- 2) The soldering gun tip shall not touch this product directly.

Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

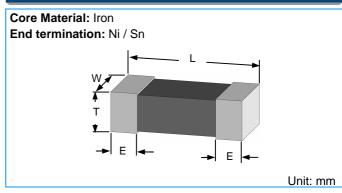
Precaution for Handling of Substrate

Do not exceed to bend the board after soldering this product extremely. (reference examples)

- I Mounting place must be as far as possible from the position, which is close to the break line of board, or on the line of large holes of board.
- I Do not bend extremely the board, in mounting another component. If necessary, use back-up pin (support pin) to prevent from bending extremely.
- I Do not break the board by hand. We recommend to use the machine or the jig to break it.

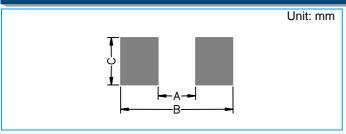
Reflow Con	Pb free assembly		
	-Temperature Min (T _{s(min)})	+150°C	
Pre Heat	-Temperature Max (T _{s(max)})	+200°C	
	-Time (min to max) (T _s)	60 -180 Seconds	
Average ramp up rate (Liquidus Temp T _L) to peak		3°C/Second Max	
T _{S(max)} to T _L - Ramp-up Rate		3°C/Second Max	
Reflow	- Temperature (T _L) (Liquidus)	+217°C	
	- Time (min to max) (T _L)	60 -150 Seconds	
Peak Temperature (T _P)		260 +0/-5°C	
Time within 5°C of actual peak Temperature (T _P)		20-40 Seconds	
Ramp-down Rate		6°C/Second Max	
Time 25°C t	8 minutes Max		

Construction & Dimensions



L	W	Т	Е
2.5±0.2	2.0±0.2	1.2 Max	0.6±0.2

Recommended Pad Layout



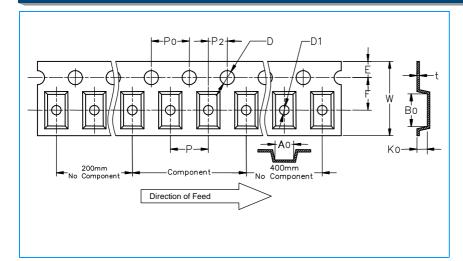
A	В	С
1.2	2.8	2.0





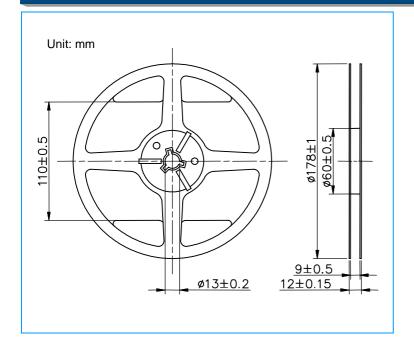
SCWL252012 Series

Tape Specifications



Symbol	252012
w	8.00±0.3
E	1.75±0.10
F	3.50±0.05
D	1.55±0.05
Р	4.00±0.10
P0	4.00±0.10
P2	2.00±0.05
A0	2.50±0.10
В0	3.00±0.10
K0	1.60±0.10
t	0.25±0.05

Reel Specifications & Packaging



Part Size (EIA Size)	Packaging Option	Quantity
2520 (1008)	7"Reel	3,000

The Contents of a box: 252010(1008): 6 reels / inner box





SCWL252012 Series

Reliability and Test Condition

Test Item	Test Condition	Criteria
Resistance to Solder Heat	 Solder temperature : 260±5°C Flux : Rosin DIP time : 10±1 sec 	 More than 95 % of terminal electrode should be covered with new solder No mechanical damage Induction value should be within ±20 % of the initial value
Adhesive Test	 Reflow temperature : 245°C It shall be Soldered on the substrate applying direction parallel to the substrate Apply force(F) : 5 N Test time : 10 sec 	 No mechanical damage Soldering the products on PCB after the pulling test force > 5 N
Temperature Cycle	 Temperature: -50 ~ +125°C for 30 minutes each Cycle: 500 cycles Measurement: At ambient temperature 24 hours after test completion 	 No mechanical damage Induction value should be within ±20 % of the initial value
Dry Heat Test	 Temperature: 85°C±5°C Test time: 500 hours Apply current: full rated current Measurement: At ambient temperature 24 hours after test completion 	No mechanical damage Induction value should be within ±20 % of the initial value
Humidity Test	 Temperature: 60°C±2°C Humidity: 90 ~ 95 % RH Apply current: full rated current Test time: 500 hours Measurement: At ambient temperature 24 hours after test completion 	No mechanical damage Induction value should be within ±20 % of the initial value